

MEG-01-004



November 24, 2004

2827
PAs

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Ave
Poughkeepsie, NY 12603

Subject: | Serial No. 09/837,007 04/18/01 |
| Mou-Shiung Lin |
| "A STRUCTURE AND MANUFACTURING |
| METHOD OF A CHIP SCALE PACKAGE" |
Grp. Art Unit: 2827 D. Zarneke

RESPONSE PATENT OFFICE ACTION

Dear Sir:

In response to the Office Action dated August 24, 2004,
please consider the following remarks regarding the above-
identified application for patent:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents, P.O.
Box 1450, Alexandria, VA 22313-1450, on November 24, 2004.

Douglas R. Schnabel, Reg. No. 47,927

Signature

Douglas R. Schnabel

Date

11-24-04